



日本電子機械工業会規格
Standard of Electronic Industries Association of Japan

EIAJ ED-7311-5A

**集積回路パッケージ個別規格
(SRAM/Flash用FBGA)**
Standard of integrated circuits package
[SRAM/Flash Fine-pitch Ball Grid Array(FBGA)]

1998年4月制定

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作 成

半導体パッケージ標準化委員会
Technical Standardization Committee on Semiconductor Device Package

発 行

社団法人 日本電子機械工業会
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登録一覧表

Registration Table

パッケージ名称 : FBGA (0.80/0.75/0.65mm pitch)

Package Name

登録番号 : IC-0000-001

Registration No.

呼び寸法 E×D Nominal dimensions	端子直線間隔 Terminal pitch e		
	0.65	0.75	0.80
E=4.10~12.00 D=5.40~15.00	48-001-AA		
E=4.60~12.00 D=6.10~15.00		48-001-AB	
6.00×8.00			48-001-AC 48-001-AD 48-001-AE
6.00×10.00			32-001-BA
10.00×8.00			56-001-CA
8.00×8.00			64-001-DA
9.00×9.00			65001-EA
8.00×10.00			68-001-FA
11.00×8.00			72-001-GA
8.00×11.00			73-001-HA
9.00×11.00			73-001-HB
9.00×12.00			73-001-HC
9.00×14.00			77-001-IA

注 表中の数値は、「(端子数n) - (連番) - (整理番号)」を示す。

Note: Numerals in the Table indicate "(Terminal number n) - (Consecutive number) - (Serial number)"

 	EIAJ STANDARD PACKAGE OUTLINE DRAWINGS	DATE 99-07-21	SHEET 1/11
PACKAGE NAME FBGA		EIAJ REGISTRATION NO. IC-0000-001	